



About STATS ChipPAC

STATS ChipPAC (SGX-ST: STATSchP) is a leading service provider of semiconductor packaging design, bump, probe, assembly, test and distribution solutions. We have the scale to provide a comprehensive range of semiconductor packaging and test solutions to a diversified global customer base servicing the computing, communications and consumer markets.

Technology and Services

With a broad technology portfolio ranging from leadframe to laminate, flip chip, wafer level and advanced 3D packaging solutions, STATS ChipPAC provides innovative and cost effective semiconductor solutions. STATS ChipPAC has a leadership position in advanced package technology including fan-in and fan-out wafer-level packaging, flip chip interconnect, 3D integration and Through Silicon Via (TSV) to meet the increasing market demand for next-generation devices with higher levels of integration, increased functionality and compact sizes.

As a full turnkey service provider, STATS ChipPAC provides wafer probe and final testing on a diverse selection of testers covering the major test platforms in the industry and has proven expertise in testing a broad range of semiconductors, especially mixed-signal, radio frequency (RF), analog and high-performance digital devices.



Business Highlights

Operations

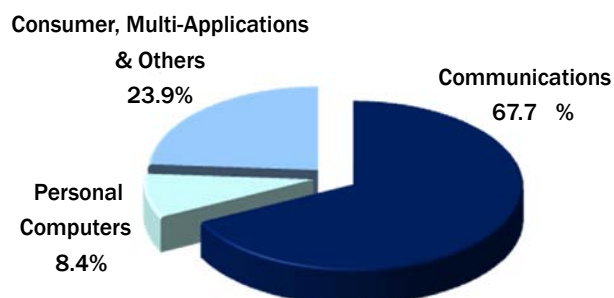
STATS ChipPAC's manufacturing facilities are located in strategic semiconductor markets including South Korea, Singapore, China and Taiwan. Our close proximity to the major hubs of wafer fabrication allows us to provide customers with fully-integrated, multi-site packaging and test services.

We market our services through a direct sales force and customer support teams in the United States, Singapore, South Korea, China, Taiwan and Switzerland.

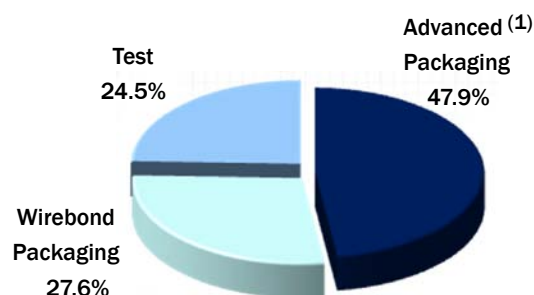


Note: 3,512 wire bonders and 880 testers as of 4Q 2014

4Q 2014 Revenue by End User Market



4Q 2014 Revenue by Product Line



(1) Advanced Packaging includes flip chip and wafer level packaging.

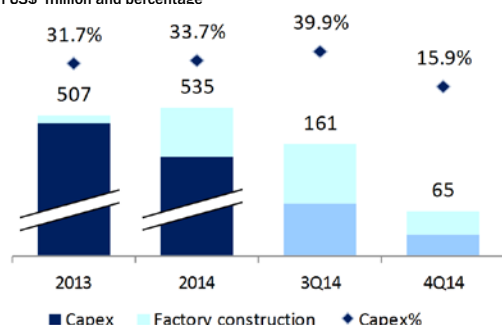
Financial Highlights

4Q 2014 Financial Results

- 4Q 2014 revenue increased by 0.7% over prior quarter
- Higher wireless communications revenue driven by new high-end smartphone ramps and stronger than seasonal demand in China's lower tier smartphones
- Solid business momentum with continued growth in advanced packaging business

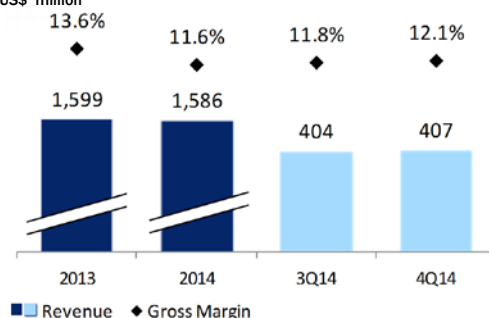
Capex and Capex as % of Revenue

In US\$ million and percentage



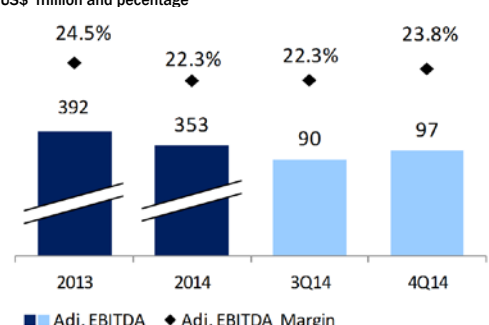
Revenue and Gross Margin

In US\$ million



Adjusted Earnings Before Interest, Taxes, Depreciation and Amortization (EBITDA)⁽¹⁾

In US\$ million and percentage



Note: (1) Adjusted EBITDA is defined as net income attributable to STATS ChipPAC Ltd. plus income tax expense, interest expense, net, depreciation and amortisation, restructuring charges, share-based compensation, asset impairment, tender offer, debt exchange or debt redemption expenses and write-off of debt issuance costs. Adjusted EBITDA excludes the plant closure costs related to our Malaysia plant.

Recent Headlines

- 1 Jan 15 STATS ChipPAC Announces Plan to Relocate China Manufacturing Operation
- 30 Dec 14 Pre-Conditional Voluntary Offer by Jiangsu Changjiang Electronics Technology Co., Ltd. (JCET) to Acquire all the Shares in STATS ChipPAC Ltd.
- 17 Dec 14 STATS ChipPAC Receives Top 20 Semiconductor Manufacturing Patent Ranking for Fourth Consecutive Year
- 20 Aug 14 STATS ChipPAC's fcCuBE® Technology Surpasses 100 Million Unit Milestone

Corporate Information

Executive Management

Tan Lay Koon, Director, President and Chief Executive Officer
 Dr. Han Byung Joon, Executive VP and Chief Technology Officer
 Hal Lasky, Executive VP and Chief Sales Officer
 Dennis Chia Choon Hwee, Senior VP and Chief Financial Officer
 Janet Taylor, Senior VP, General Counsel and Company Secretary

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Stock Information

Singapore Exchange Securities
 Trading Limited (SGX-ST)
 Ticker: STATSchP

